

## QUAD CHANNEL M-LVDS RECEIVERS

Check for Samples: [SN65MLVD048](#)

### FEATURES

- Low-Voltage Differential 30-Ω to 55-Ω Line Receivers for Signaling Rates<sup>(1)</sup> up to 250Mbps; Clock Frequencies up to 125MHz
- Type-1 Receiver Incorporates 25 mV of Input Threshold Hysteresis
- Type-2 Receiver Provides 100 mV Offset Threshold to Detect Open-Circuit and Idle-Bus Conditions
- Wide Receiver Input Common-Mode Voltage Range, -1 V to 3.4 V, Allows 2 V of Ground Noise
- Meets or Exceeds the M-LVDS Standard TIA/EIA-899 for Multipoint Topology
- High Input Impedance when  $V_{CC} \leq 1.5V$
- Enhanced ESD Protection: 7 kV HBM on all pins
- 48-Pin 7 X 7 QFN (RGZ)

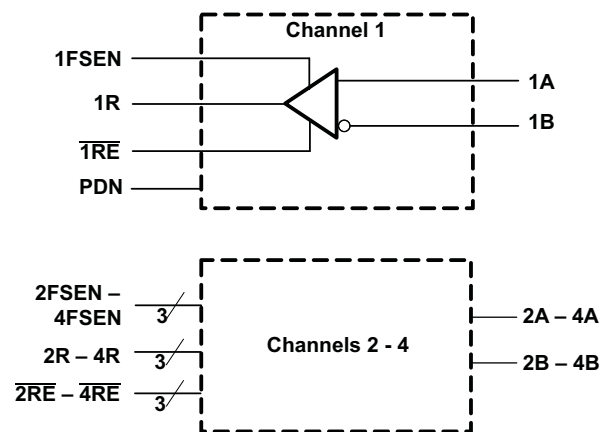
<sup>(1)</sup> The signaling rate of a line is the number of voltage transitions that are made per second, expressed in the units bps (bits per second).

### APPLICATIONS

- Parallel Multipoint Data and Clock Transmission via Backplanes and Cables
- Cellular Base Stations
- Central Office Switches
- Network Switches and Routers

### LOGIC DIAGRAM (POSITIVE LOGIC)

LOGIC DIAGRAM (POSITIVE LOGIC)  
SN65MLVD048



### DESCRIPTION

The SN65MLVD048 is a quad-channel M-LVDS receiver. This device is designed in full compliance with the TIA/EIA-899 (M-LVDS) standard, which is optimized to operate at signaling rates up to 250 Mbps. Each receiver channel is controlled by a receive enable ( $\overline{RE}$ ). When  $\overline{RE}$  = low, the corresponding channel is enabled; when  $\overline{RE}$  = high, the corresponding channel is disabled.

The M-LVDS standard defines two types of receivers, designated as Type-1 and Type-2. Type-1 receivers have thresholds centered about zero with 25 mV of hysteresis to prevent output oscillations with loss of input; Type-2 receivers implement a failsafe by using an offset threshold. Receiver outputs are slew rate controlled to reduce EMI and crosstalk effects associated with large current surges.

The devices are characterized for operation from -40°C to 85°C.



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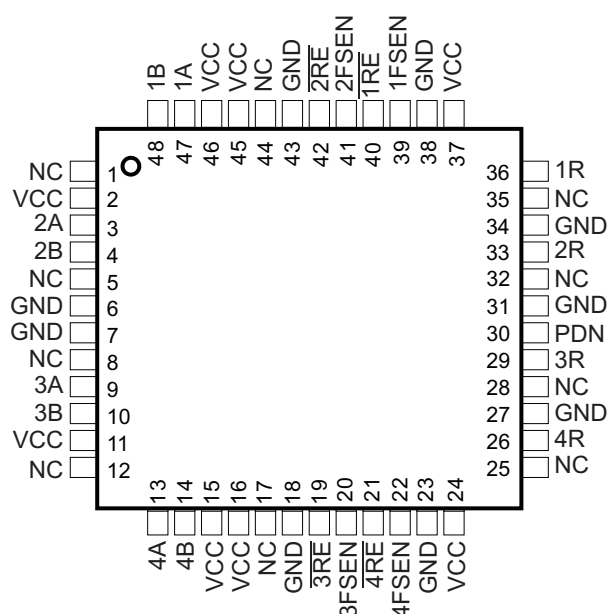
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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## PIN FUNCTIONS

| PIN             |                                  | I/O | DESCRIPTION                                                                                                                                                                                                                                                               |
|-----------------|----------------------------------|-----|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| NAME            | NO.                              |     |                                                                                                                                                                                                                                                                           |
| 1R–4R           | 36, 33, 29, 26                   | O   | Data output from receivers                                                                                                                                                                                                                                                |
| 1A–4A           | 47, 3, 9, 13                     | I/O | M-LVDS bus non-inverting input/output                                                                                                                                                                                                                                     |
| 1B–4B           | 48, 4, 10, 14                    | I/O | M-LVDS bus inverting input/output                                                                                                                                                                                                                                         |
| GND             | 6, 7, 18, 23, 27, 31, 34, 38, 43 | I   | Circuit ground. <b>ALL GND pins must be connected to ground.</b>                                                                                                                                                                                                          |
| V <sub>CC</sub> | 2, 11, 15, 16, 24, 37, 45, 46    | I   | Supply voltage. <b>ALL VCC pins must be connected to supply.</b>                                                                                                                                                                                                          |
| 1RE–4RE         | 40, 42, 19, 21                   | I   | Receiver enable, active low, enables individual receivers. When this pin is left floating, internally this pin will be pulled to logic HIGH.                                                                                                                              |
| 1FSEN–4FSEN     | 39, 41, 20, 22                   | I   | <p>Failsafe enable pin. When this pin is left floating, internally this pin will be pulled to logic HIGH.</p> <p>This pin enables the Type 2 receiver for the respective channel.</p> <p>xFSEN = L → Type 1 receiver inputs</p> <p>xFSEN = H → Type 2 receiver inputs</p> |
| PDN             | 30                               |     | <p>Power Down pin. When this pin is left floating, internally this pin will be pulled to logic LOW.</p> <p>When PDN is HIGH, the device is powered up.</p> <p>When PDN is LOW, the device overrides all other control and powers down. All outputs are Hi-Z</p>           |
| NC              | 1, 5, 8, 12, 17, 25, 28, 32, 35  |     | Not Connected                                                                                                                                                                                                                                                             |
| NC              | 44                               |     | Not Connected. Internal TI Test pin. <b>This pin must be left unconnected.</b>                                                                                                                                                                                            |
| PowerPAD™       | –                                |     | Connected to GND                                                                                                                                                                                                                                                          |

## RGZ PACKAGE (TOP VIEW)



**Table 1. DEVICE FUNCTION TABLE**

| INPUTS <sup>(1)</sup>                           |     |      |                 | RECEIVER TYPE | OUTPUT <sup>(1)</sup> |
|-------------------------------------------------|-----|------|-----------------|---------------|-----------------------|
| $V_{ID} = V_A - V_B$                            | PDN | FSEN | $\overline{RE}$ |               | R                     |
| $V_{ID} > 35 \text{ mV}$                        | H   | L    | L               | Type 1        | H                     |
| $-35 \text{ mV} \leq V_{ID} \leq 35 \text{ mV}$ | H   | L    | L               | Type 1        | ?                     |
| $V_{ID} < -35 \text{ mV}$                       | H   | L    | L               | Type 1        | L                     |
| $V_{ID} > 135 \text{ mV}$                       | H   | H    | L               | Type 2        | H                     |
| $65 \text{ mV} \leq V_{ID} \leq 135 \text{ mV}$ | H   | H    | L               | Type 2        | ?                     |
| $V_{ID} < 65 \text{ mV}$                        | H   | H    | L               | Type 2        | L                     |
| Open Circuit                                    | H   | L    | L               | Type 1        | ?                     |
| Open Circuit                                    | H   | H    | L               | Type 2        | L                     |
| X                                               | H   | X    | H               | X             | Z                     |
| X                                               | H   | X    | OPEN            | X             | Z                     |
| X                                               | L   | X    | X               | X             | Z                     |

(1) H=high level, L=low level, Z=high impedance, X=Don't care, ?=indeterminate

**ORDERING INFORMATION<sup>(1)</sup>**

| PART NUMBER     | FUNCTION                     | PART MARKING | PACKAGE / CARRIER                |
|-----------------|------------------------------|--------------|----------------------------------|
| SN65MLVD048RGZR | M-LVDS Type 1 and 2 Receiver | MLVD048      | 48-Pin QFN / Tape and Reel       |
| SN65MLVD048RGZT |                              | MLVD048      | 48-Pin QFN / Small Tape and Reel |

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at [www.ti.com](http://www.ti.com).

**PACKAGE DISSIPATION RATINGS<sup>(1)</sup>**

| PACKAGE          | PCB TYPE | $T_A \leq 25^\circ\text{C}$<br>POWER RATING | DERATING FACTOR <sup>(2)</sup><br>ABOVE $T_A = 25^\circ\text{C}$ | $T_A = 85^\circ\text{C}$<br>POWER RATING |
|------------------|----------|---------------------------------------------|------------------------------------------------------------------|------------------------------------------|
| 48-Pin QFN (RGZ) | Low-K    | 1298 mW                                     | 12.98 mW/°C                                                      | 519 mW                                   |
|                  | High-K   | 3448 mW                                     | 34.48 mW/°C                                                      | 1379 mW                                  |

(1) The thermal dissipations are in the consideration of soldering down the powerPAD without via on each type of boards.

(2) This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

**THERMAL CHARACTERISTICS**

| PARAMETER                                            | TEST CONDITIONS                                                                     | MIN | TYP  | MAX | UNIT |
|------------------------------------------------------|-------------------------------------------------------------------------------------|-----|------|-----|------|
| $R_{\theta JB}$ Junction-to-board thermal resistance |                                                                                     |     | 9    |     | °C/W |
| $R_{\theta JC}$ Junction-to-case thermal resistance  |                                                                                     |     | 20   |     | °C/W |
| $R_{\theta JP}$ Junction-to-pad thermal resistance   |                                                                                     |     | 1.37 |     | °C/W |
| $P_D$ Device power dissipation                       | $\overline{RE}$ at 0 V, $C_L = 15 \text{ pF}$ , $V_{ID} = 400 \text{ mV}$ , 125 MHz |     |      | 339 | mW   |

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## ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

|                         |                                     |                | VALUE     | UNIT |
|-------------------------|-------------------------------------|----------------|-----------|------|
| V <sub>CC</sub>         | Supply voltage range <sup>(2)</sup> |                | –0.5 to 4 | V    |
| Input voltage range     | $\overline{RE}$ , FSEN              |                | –0.5 to 4 | V    |
|                         | A or B                              |                | –1.8 to 4 | V    |
| Output voltage range    | R                                   |                | –0.3 to 4 | V    |
| Electrostatic discharge | Human-body model <sup>(3)</sup>     | All other pins | ±7        | kV   |
|                         | Charged-device model <sup>(4)</sup> | All pins       | ±1.5      | kV   |

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.
- (3) Tested in accordance with JEDEC Standard 22, Test Method A114-E. Bus pin stressed with respect to a common connection of GND and V<sub>CC</sub>.
- (4) Tested in accordance with EIA-JEDEC JESD22-C101D.

## RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

|                                  |                                         | MIN  | NOM | MAX             | UNIT |
|----------------------------------|-----------------------------------------|------|-----|-----------------|------|
| V <sub>CC</sub>                  | Supply voltage                          | 3    | 3.3 | 3.6             | V    |
| V <sub>IH</sub>                  | High-level input voltage                | 2    |     | V <sub>CC</sub> | V    |
| V <sub>IL</sub>                  | Low-level input voltage                 | GND  |     | 0.8             | V    |
| V <sub>A</sub> or V <sub>B</sub> | Voltage at any bus terminal             | –1.4 |     | 3.8             | V    |
| V <sub>ID</sub>                  | Magnitude of differential input voltage | 0.05 |     | V <sub>CC</sub> | V    |
| V <sub>IC</sub>                  | Differential common-mode input voltage  | –1   |     | 3.4             | V    |
| R <sub>L</sub>                   | Differential load resistance            | 30   | 50  |                 | Ω    |
| 1/t <sub>UI</sub>                | Signaling rate                          |      |     | 250             | Mbps |
| T <sub>A</sub>                   | Operating free-air temperature          | –40  |     | 85              | °C   |

## DEVICE ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

| PARAMETER       |                | TEST CONDITIONS                                                                                      |  | MIN | TYP <sup>(1)</sup> | MAX | UNIT |
|-----------------|----------------|------------------------------------------------------------------------------------------------------|--|-----|--------------------|-----|------|
| I <sub>CC</sub> | Supply current | $\overline{RE}$ at 0 V for all channels<br>C <sub>L</sub> = 15 pF, V <sub>ID</sub> = 400 mV, 125 MHz |  |     | 86                 | 94  | mA   |
|                 | Power down     | PDN = L                                                                                              |  |     | 0.75               | 1.5 | mA   |

- (1) All typical values are at 25°C and with a 3.3-V supply voltage.

## RECEIVER ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

| PARAMETER                                  |                                                                                  |        | TEST CONDITIONS                                                                                                      | MIN  | TYP <sup>(1)</sup> | MAX  | UNIT |
|--------------------------------------------|----------------------------------------------------------------------------------|--------|----------------------------------------------------------------------------------------------------------------------|------|--------------------|------|------|
| V <sub>IT+</sub>                           | Positive-going differential input voltage threshold                              | Type 1 | See <a href="#">Table 2</a> and <a href="#">Table 3</a>                                                              |      |                    | 35   | mV   |
|                                            |                                                                                  | Type 2 |                                                                                                                      |      |                    | 135  |      |
| V <sub>IT-</sub>                           | Negative-going differential input voltage threshold                              | Type 1 |                                                                                                                      |      |                    | –35  | mV   |
|                                            |                                                                                  | Type 2 |                                                                                                                      |      |                    | 65   |      |
| V <sub>HYS</sub>                           | Differential input voltage hysteresis (V <sub>IT+</sub> – V <sub>IT-</sub> )     | Type 1 |                                                                                                                      |      |                    | 25   | mV   |
|                                            |                                                                                  | Type 2 |                                                                                                                      |      |                    | 0    |      |
| V <sub>OH</sub>                            | High-level output voltage                                                        |        | I <sub>OH</sub> = –8 mA                                                                                              | 2.4  |                    |      | V    |
| V <sub>OL</sub>                            | Low-level output voltage                                                         |        | I <sub>OL</sub> = 8 mA                                                                                               |      |                    | 0.4  | V    |
| I <sub>IH</sub>                            | High-level input current                                                         |        | V <sub>IH</sub> = 2 V to V <sub>CC</sub>                                                                             | –10  |                    |      | μA   |
| I <sub>IL</sub>                            | Low-level input current                                                          |        | V <sub>IL</sub> = GND to 0.8 V                                                                                       | –10  |                    |      | μA   |
| I <sub>OZ</sub>                            | High-impedance output current                                                    |        | V <sub>O</sub> = 0 V or V <sub>CC</sub>                                                                              | –10  |                    | 15   | μA   |
| I <sub>A</sub> or I <sub>B</sub>           | Receiver input current                                                           |        | One input (V <sub>A</sub> or V <sub>B</sub> ) = –1.4 V or 3.8 V, Other input = 1.2 V                                 | –20  |                    | 20   | μA   |
| I <sub>AB</sub>                            | Receiver differential input current (I <sub>A</sub> – I <sub>B</sub> )           |        | V <sub>A</sub> = V <sub>B</sub> = –1.4 V or 3.8 V                                                                    | –4   |                    | 4    | μA   |
| I <sub>A(OFF)</sub> or I <sub>B(OFF)</sub> | Receiver input current                                                           |        | One input (V <sub>A</sub> or V <sub>B</sub> ) = –1.4 V or 3.8 V, Other input = 1.2 V, V <sub>CC</sub> = GND or 1.5 V | –32  |                    | 32   | μA   |
| I <sub>AB(OFF)</sub>                       | Receiver power-off differential input current (I <sub>A</sub> – I <sub>B</sub> ) |        | V <sub>A</sub> = V <sub>B</sub> = –1.4 V or 3.8 V, V <sub>CC</sub> = GND or 1.5 V                                    | –4   |                    | 4    | μA   |
| C <sub>A</sub> or C <sub>B</sub>           | Input capacitance                                                                |        | V <sub>I</sub> = 0.4sin(30E6πt) + 0.5V, <sup>(2)</sup> Other input at 1.2 V                                          |      | 5                  |      | pF   |
| C <sub>AB</sub>                            | Differential input capacitance                                                   |        | V <sub>AB</sub> = 0.4sin(30E6πt) + 0.5 V <sup>(2)</sup>                                                              |      |                    | 3    | pF   |
| C <sub>A/B</sub>                           | Input capacitance balance, (C <sub>A</sub> /C <sub>B</sub> )                     |        |                                                                                                                      | 0.99 |                    | 1.01 |      |

(1) All typical values are at 25°C and with a 3.3-V supply voltage.

(2) HP4194A impedance analyzer (or equivalent)

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## RECEIVER SWITCHING CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

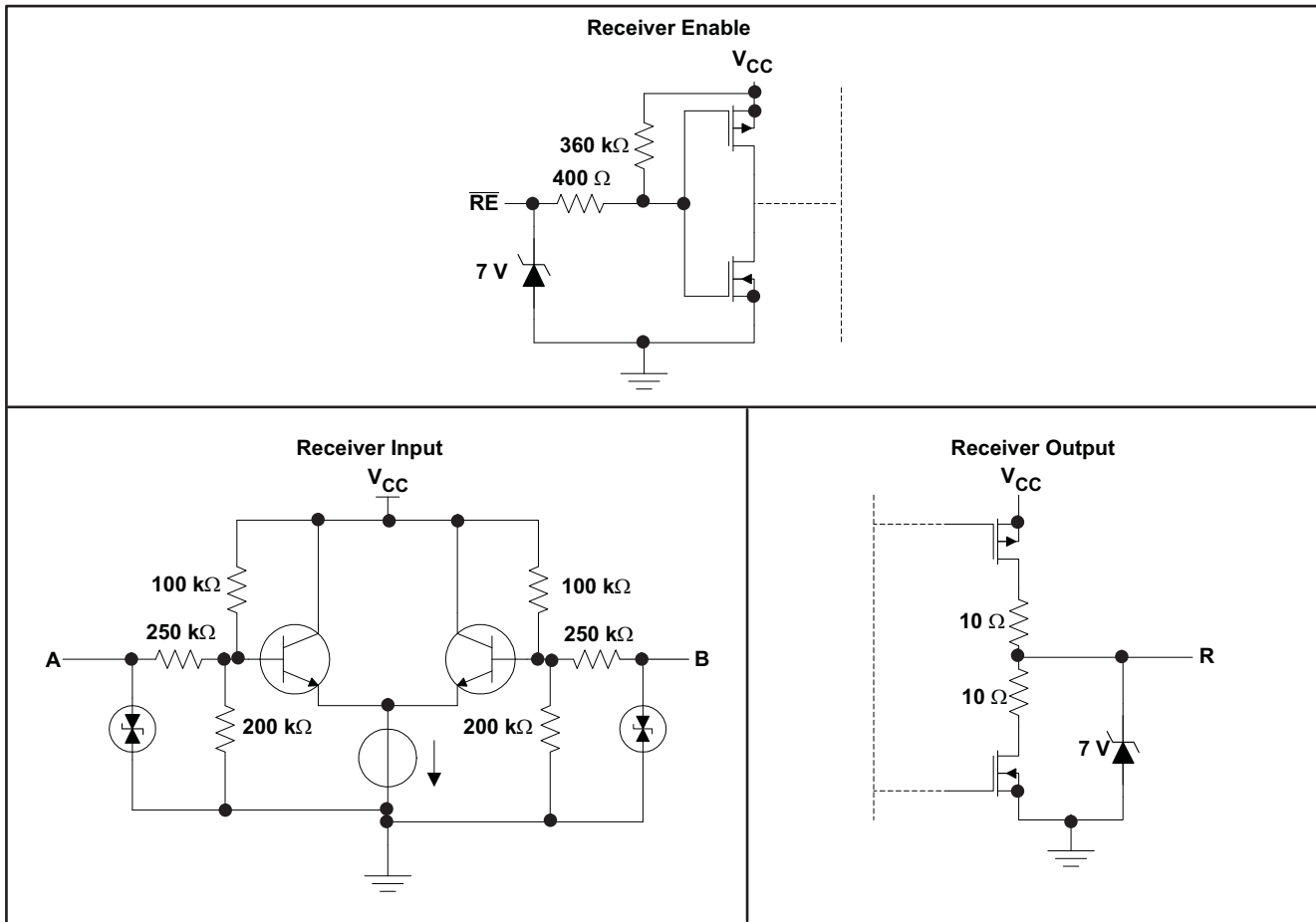
| PARAMETER             |                                                          |                   | TEST CONDITIONS                                                                                              | MIN | TYP <sup>(1)</sup> | MAX | UNIT |
|-----------------------|----------------------------------------------------------|-------------------|--------------------------------------------------------------------------------------------------------------|-----|--------------------|-----|------|
| t <sub>PLH</sub>      | Propagation delay time, low-to-high-level output         |                   | C <sub>L</sub> = 15 pF, See <a href="#">Figure 2</a>                                                         | 2   |                    | 6   | ns   |
| t <sub>PHL</sub>      | Propagation delay time, high-to-low-level output         |                   |                                                                                                              | 2   |                    | 6   | ns   |
| t <sub>r</sub>        | Output signal rise time                                  |                   |                                                                                                              | 1   |                    | 2.3 |      |
| t <sub>f</sub>        | Output signal fall time                                  |                   |                                                                                                              | 1   |                    | 2.3 | ns   |
| t <sub>sk(p)</sub>    | Pulse skew ( t <sub>PHL</sub> – t <sub>PLH</sub>  )      | Type 1            |                                                                                                              |     | 35                 | 270 | ps   |
|                       |                                                          | Type 2            |                                                                                                              |     | 150                | 460 |      |
| t <sub>sk(pp)</sub>   |                                                          | Part-to-part skew |                                                                                                              |     | 800                | ps  |      |
| t <sub>jit(per)</sub> | Period jitter, rms (1 standard deviation) <sup>(2)</sup> |                   | All channels switching, 125 MHz clock input <sup>(3)</sup> , See <a href="#">Figure 4</a>                    |     |                    | 6   | ps   |
| t <sub>jit(c-c)</sub> | Cycle-to-cycle jitter, rms <sup>(2)</sup>                |                   |                                                                                                              |     |                    | 13  | ps   |
| t <sub>jit(det)</sub> | Deterministic jitter <sup>(2)</sup>                      | Type 1            | All channels switching, 250 Mbps 2 <sup>15</sup> -1 PRBS input <sup>(3)</sup> , See <a href="#">Figure 4</a> |     |                    | 800 | ps   |
|                       |                                                          | Type 2            |                                                                                                              |     |                    | 945 | ps   |
| t <sub>jit(ran)</sub> | Random jitter <sup>(2)</sup>                             | Type 1            |                                                                                                              |     |                    | 9   | ps   |
|                       |                                                          | Type 2            |                                                                                                              |     |                    | 8   | ps   |
| t <sub>PZH</sub>      | Enable time, high-impedance-to-high-level output         |                   | C <sub>L</sub> = 15 pF, See <a href="#">Figure 3</a>                                                         |     |                    | 15  | ns   |
| t <sub>PZL</sub>      | Enable time, high-impedance-to-low-level output          |                   | C <sub>L</sub> = 15 pF, See <a href="#">Figure 3</a>                                                         |     |                    | 15  | ns   |
| t <sub>PHZ</sub>      | Disable time, high-level-to-high-impedance output        |                   | C <sub>L</sub> = 15 pF, See <a href="#">Figure 3</a>                                                         |     |                    | 10  | ns   |
| t <sub>PLZ</sub>      | Disable time, low-level-to-high-impedance output         |                   | C <sub>L</sub> = 15 pF, See <a href="#">Figure 3</a>                                                         |     |                    | 10  | ns   |

(1) All typical values are at 25°C and with a 3.3-V supply voltage.

(2) Jitter is ensured by design and characterization. Stimulus jitter has been subtracted from the numbers.

(3)  $t_r = t_f = 0.5\text{ns}$  (10% to 90%)

## EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS



## PARAMETER MEASUREMENT INFORMATION

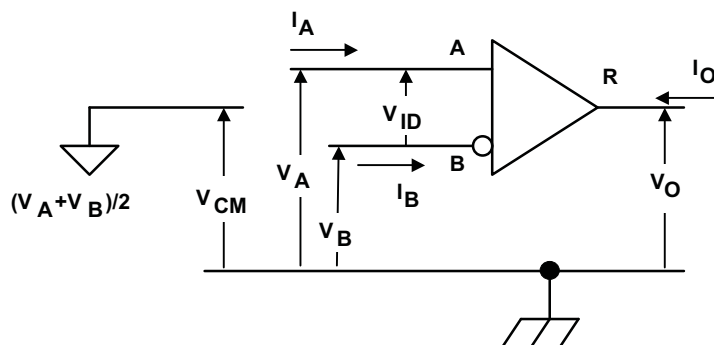


Figure 1. Receiver Voltage and Current Definitions

Table 2. Type-1 Receiver Input Threshold Test Voltages

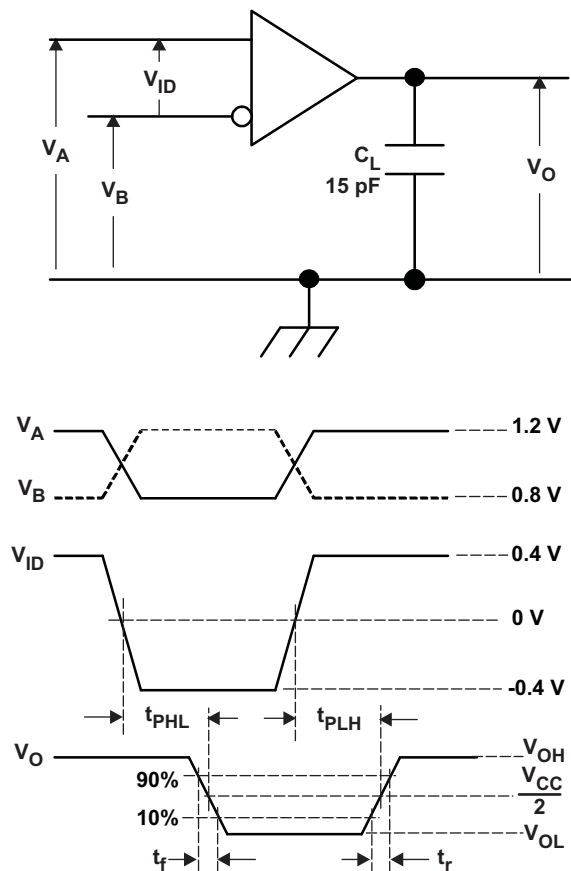
| APPLIED VOLTAGES |          | RESULTING DIFFERENTIAL<br>INPUT VOLTAGE | RESULTING<br>COMMON-MODE INPUT<br>VOLTAGE | RECEIVER<br>OUTPUT <sup>(1)</sup> |
|------------------|----------|-----------------------------------------|-------------------------------------------|-----------------------------------|
| $V_{IA}$         | $V_{IB}$ | $V_{ID}$                                | $V_{IC}$                                  |                                   |
| 2.400            | 0.000    | 2.400                                   | 1.200                                     | H                                 |
| 0.000            | 2.400    | -2.400                                  | 1.200                                     | L                                 |
| 3.400            | 3.365    | 0.035                                   | 3.3825                                    | H                                 |
| 3.365            | 3.400    | -0.035                                  | 3.3825                                    | L                                 |
| -0.965           | -1       | 0.035                                   | -0.9825                                   | H                                 |
| -1               | -0.965   | -0.035                                  | -0.9825                                   | L                                 |

(1) H= high level, L = low level, output state assumes receiver is enabled ( $\overline{RE} = L$ )

Table 3. Type-2 Receiver Input Threshold Test Voltages

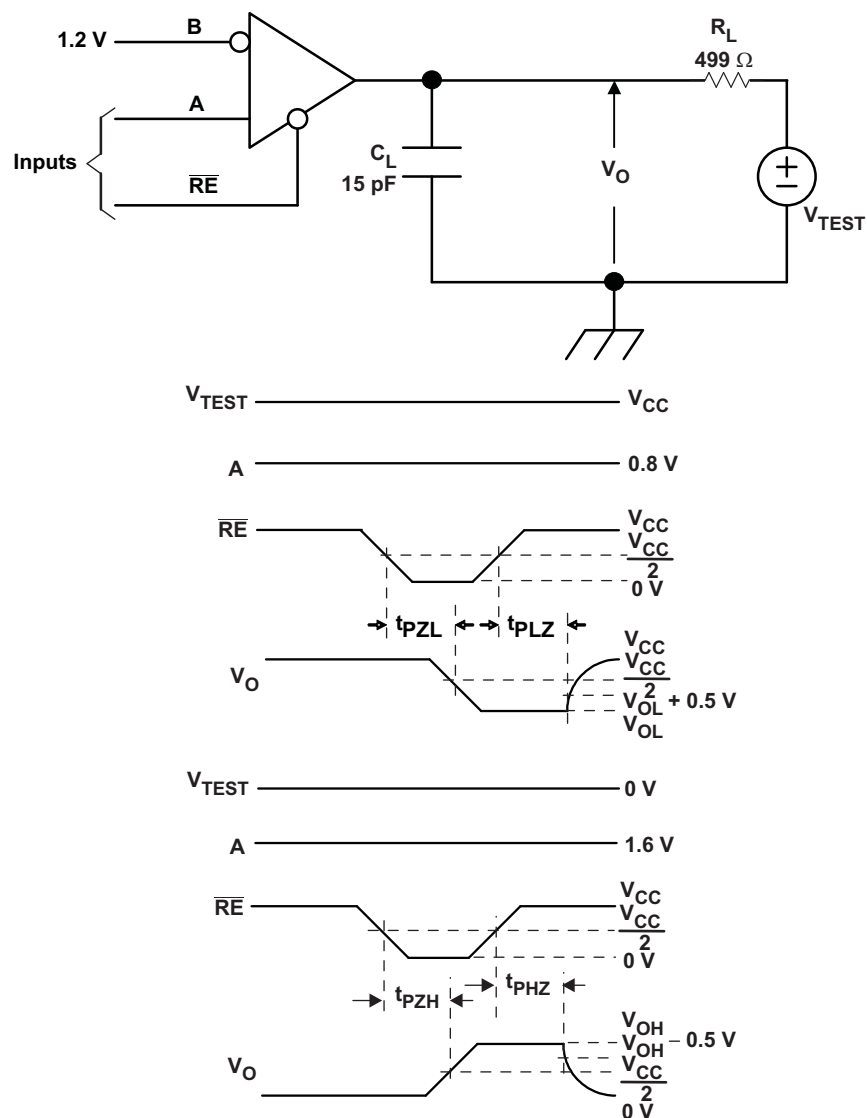
| APPLIED VOLTAGES |          | RESULTING DIFFERENTIAL<br>INPUT VOLTAGE | RESULTING<br>COMMON-MODE INPUT<br>VOLTAGE | RECEIVER<br>OUTPUT <sup>(1)</sup> |
|------------------|----------|-----------------------------------------|-------------------------------------------|-----------------------------------|
| $V_{IA}$         | $V_{IB}$ | $V_{ID}$                                | $V_{IC}$                                  |                                   |
| 2.400            | 0.000    | 2.400                                   | 1.200                                     | H                                 |
| 0.000            | 2.400    | -2.400                                  | 1.200                                     | L                                 |
| 3.400            | 3.265    | 0.135                                   | 3.3325                                    | H                                 |
| 3.4000           | 3.335    | 0.05065                                 | 3.3675                                    | L                                 |
| -0.865           | -1       | 0.135                                   | -0.9325                                   | H                                 |
| -0.935           | -1       | 0.065                                   | -0.9675                                   | L                                 |

(1) H= high level, L = low level, output state assumes receiver is enabled ( $\overline{RE} = L$ )



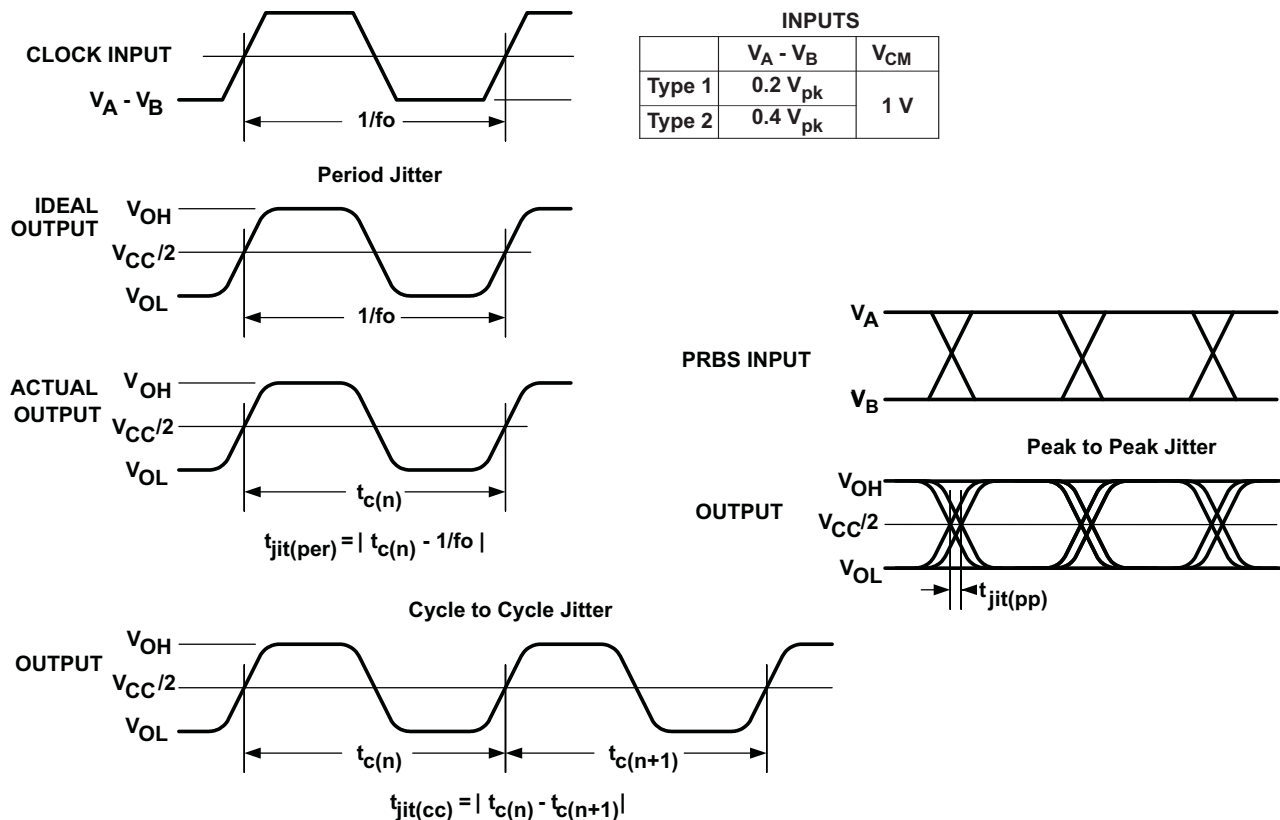
- A. All input pulses are supplied by a generator having the following characteristics:  $t_r$  or  $t_f \leq 1$  ns, Frequency = 1 MHz, duty cycle =  $50 \pm 5\%$ .  $C_L$  is a combination of a 20%-tolerance, low-loss ceramic, surface-mount capacitor and fixture capacitance within 2 cm of the D.U.T.
- B. The measurement is made on test equipment with a -3dB bandwidth of at least 1 GHz.

**Figure 2. Receiver Timing Test Circuit and Waveforms**



- All input pulses are supplied by a generator having the following characteristics:  $t_r$  or  $t_f \leq 1\text{ ns}$ , frequency =  $1\text{ MHz}$ , duty cycle =  $50 \pm 5\%$ .
- $R_L$  is 1% tolerance, metal film, surface mount, and located within 2 cm of the D.U.T
- $C_L$  is the instrumentation and fixture capacitance within 2 cm of the D.U.T. and  $\pm 20\%$ . The measurement is made on test equipment with a  $-3\text{ dB}$  bandwidth of at least  $1\text{ GHz}$ .

**Figure 3. Receiver Enable/Disable Time Test Circuit and Waveforms**



- All input pulses are supplied by the Agilent 81250 Parallel BERT Stimulus System with plug-in E4832A.
- The cycle-to-cycle jitter measurement is made on a TEK TDS6604 running TDSJIT3 application software.
- All other jitter measurements are made with an Agilent Infiniium DCA-J 86100C Digital Communications Analyzer.
- Period jitter and cycle-to-cycle jitter are measured using a 125-MHz  $50 \pm 1\%$  duty cycle clock input. Measured over 75K samples.
- Deterministic jitter and random jitter are measured using a 250-Mbps  $2^{15}-1$  PRBS input. Measured over  $BER = 10^{-12}$

**Figure 4. Receiver Jitter Measurement Waveforms**

## TYPICAL CHARACTERISTICS

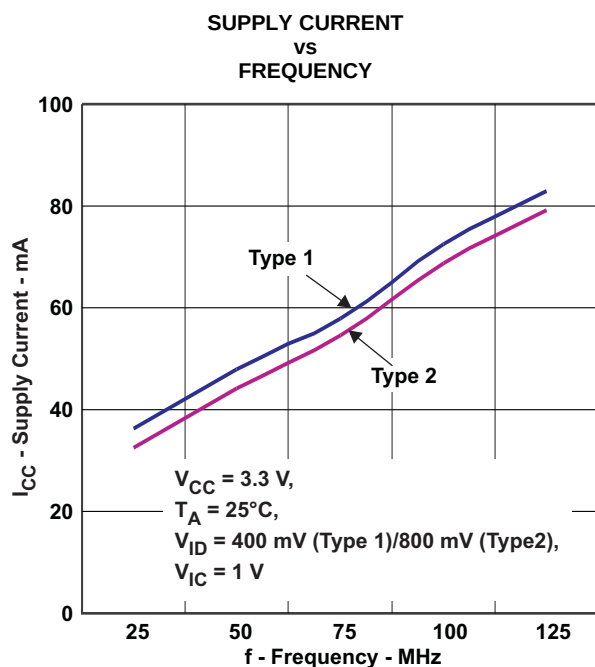


Figure 5.

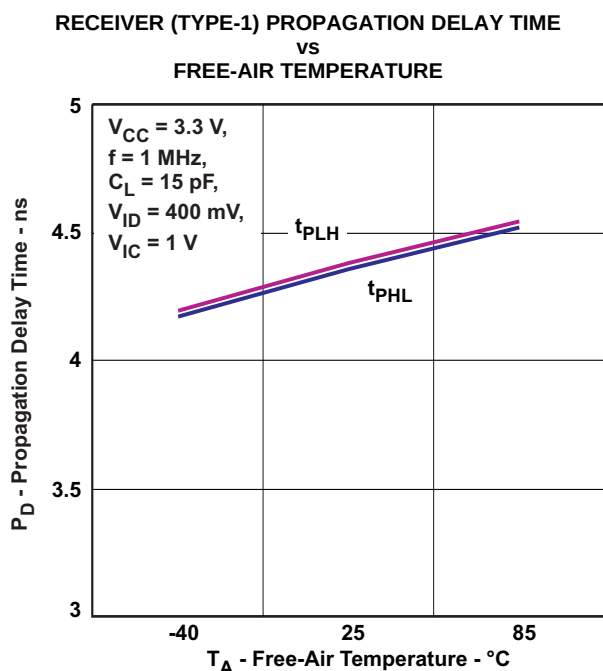


Figure 6.

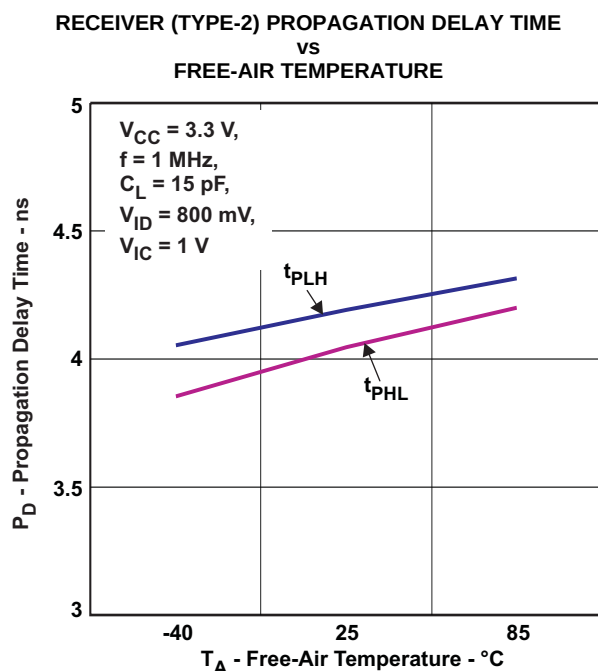


Figure 7.

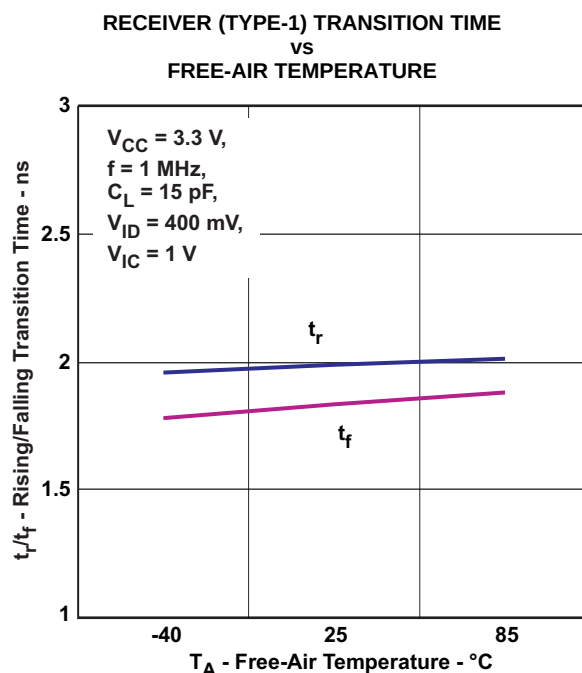


Figure 8.

## TYPICAL CHARACTERISTICS (continued)

RECEIVER (TYPE-2) TRANSITION TIME  
VS  
FREE-AIR TEMPERATURE

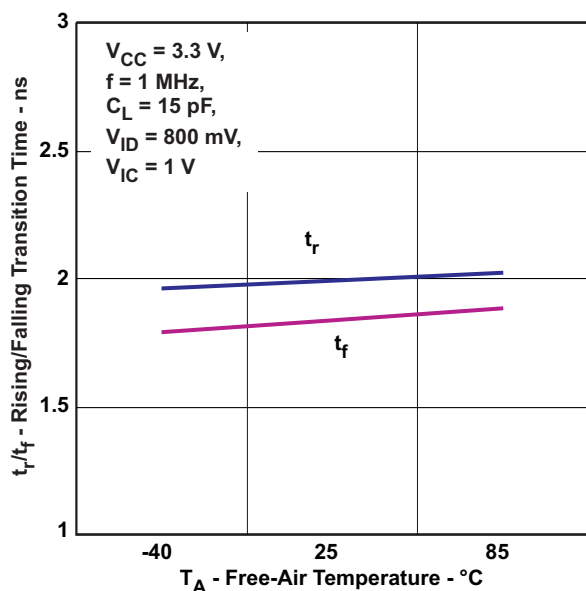


Figure 9.

RECEIVER (TYPE-1) TRANSITION TIME  
VS  
OUTPUT LOAD CAPACITOR

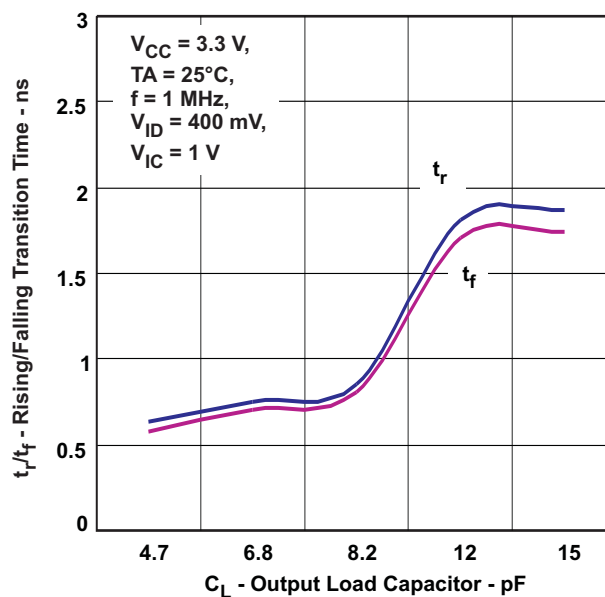


Figure 10.

RECEIVER (TYPE-2) TRANSITION TIME  
VS  
OUTPUT LOAD CAPACITOR

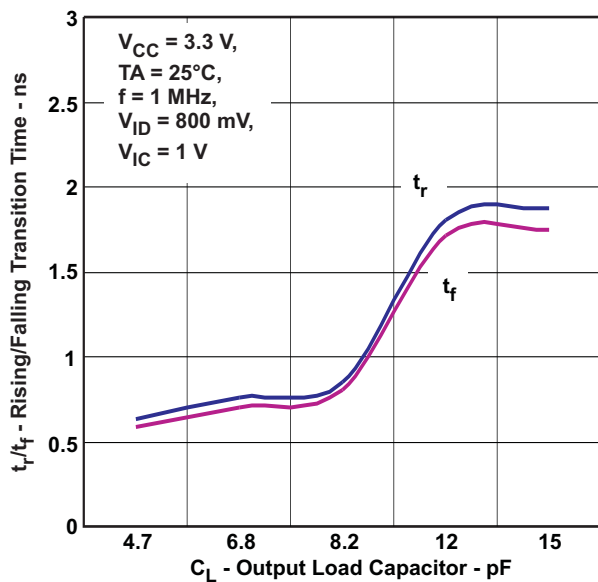


Figure 11.

ADDED RECEIVER PEAK-TO-PEAK JITTER  
VS  
SIGNALING RATE

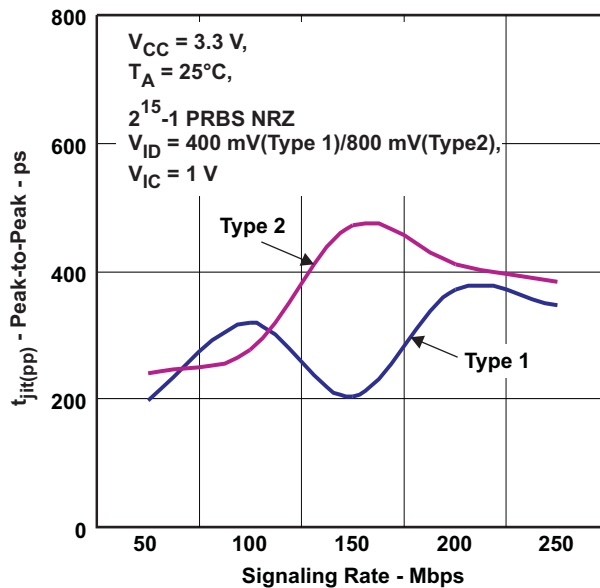


Figure 12.

## TYPICAL CHARACTERISTICS (continued)

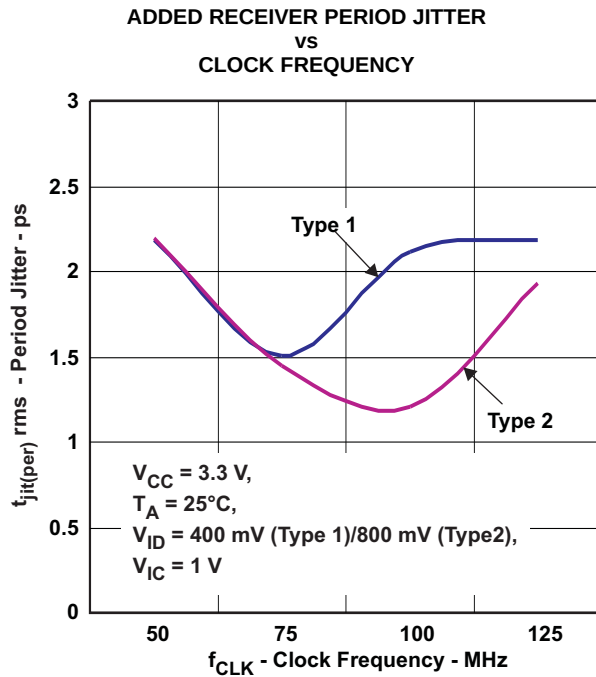


Figure 13.

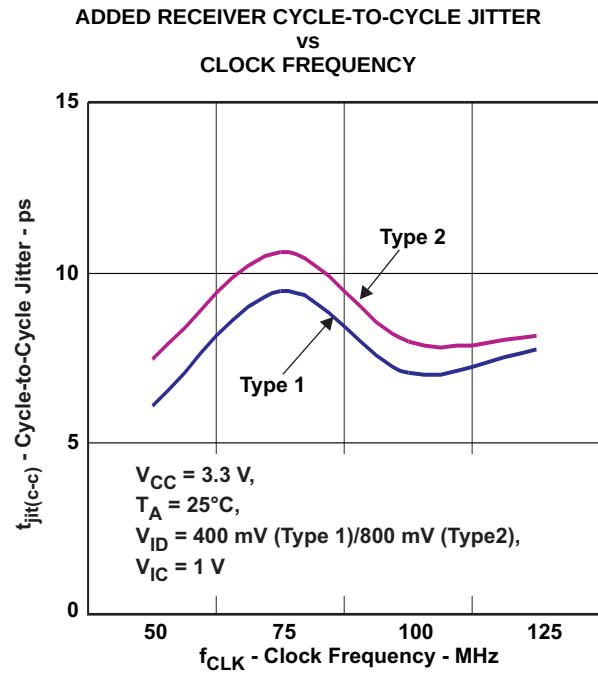


Figure 14.

## EYE PATTERNS

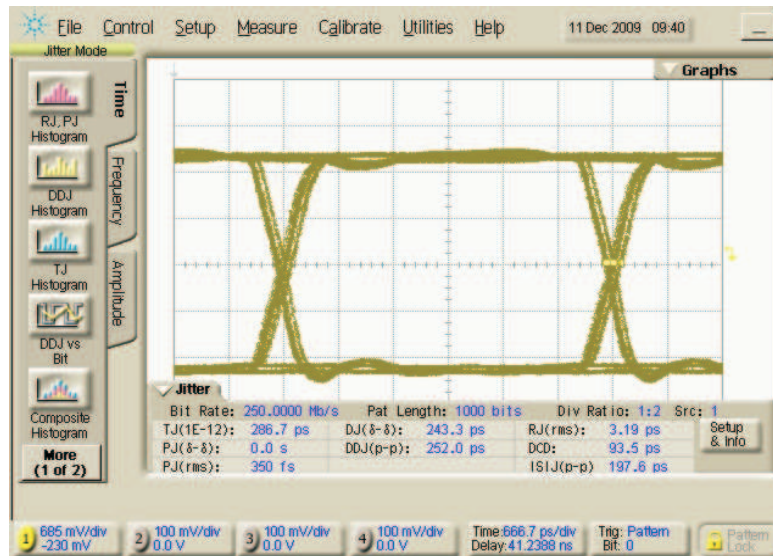


Figure 15. SN65MLVD048 Output ( $V_{CC} = 3.3$  V,  $V_{ID} = 400$  mV) 250 Mbps  $2^{15}-1$  PRBS, Receiver Type 1

## TYPICAL CHARACTERISTICS (continued)

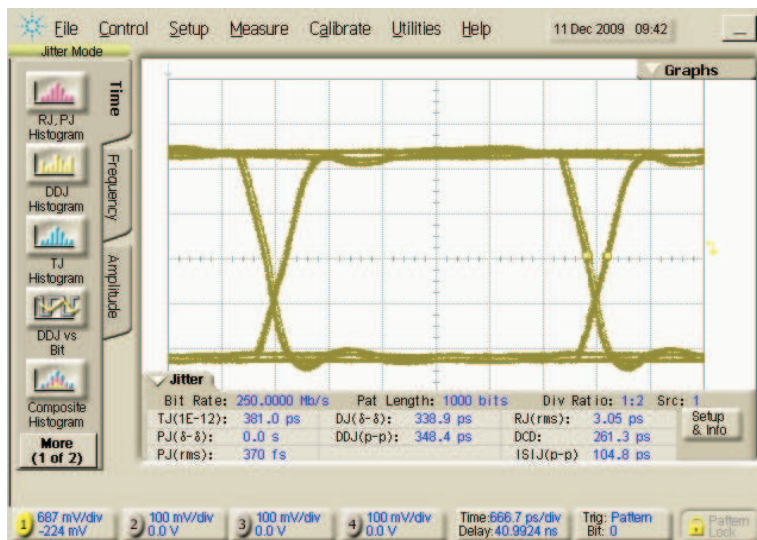


Figure 16. SN65MLVD048 Output ( $V_{CC} = 3.3\text{ V}$ ,  $V_{ID} = 800\text{ mV}$ ) 250 Mbps  $2^{15}-1$  PRBS, Receiver Type 2

## PACKAGING INFORMATION

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| SN65MLVD048RGZR  | ACTIVE        | VQFN         | RGZ                | 48   | 2500           | Green (RoHS<br>& no Sb/Br) | NIPDAU                  | Level-3-260C-168 HR  | -40 to 85    | MLVD048                 | <a href="#">Samples</a> |
| SN65MLVD048RGZT  | ACTIVE        | VQFN         | RGZ                | 48   | 250            | Green (RoHS<br>& no Sb/Br) | NIPDAU                  | Level-3-260C-168 HR  | -40 to 85    | MLVD048                 | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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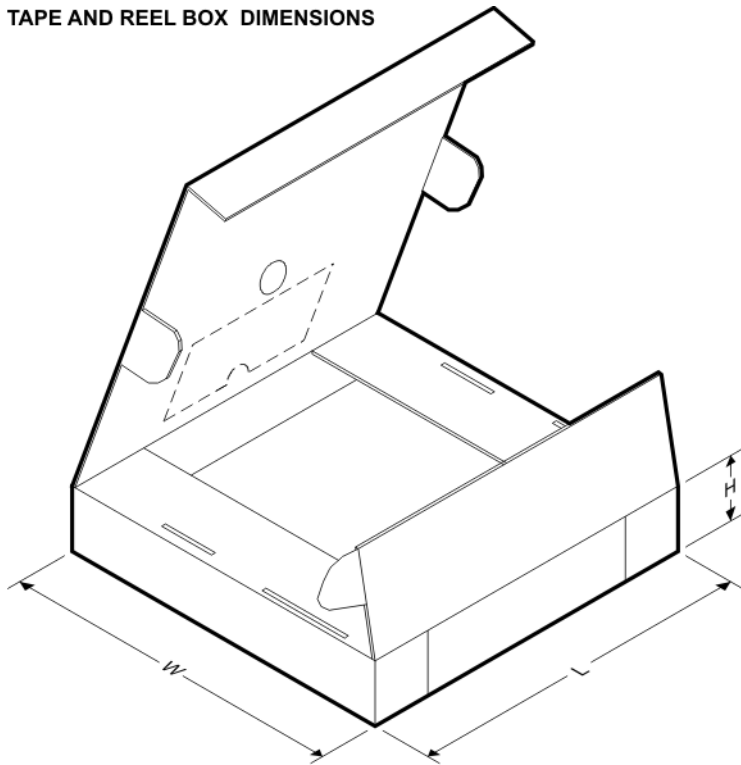


**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

| Device          | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN65MLVD048RGZR | VQFN         | RGZ             | 48   | 2500 | 330.0              | 16.4               | 7.3     | 7.3     | 1.5     | 12.0    | 16.0   | Q2            |
| SN65MLVD048RGZT | VQFN         | RGZ             | 48   | 250  | 180.0              | 16.4               | 7.3     | 7.3     | 1.5     | 12.0    | 16.0   | Q2            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device          | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN65MLVD048RGZR | VQFN         | RGZ             | 48   | 2500 | 367.0       | 367.0      | 38.0        |
| SN65MLVD048RGZT | VQFN         | RGZ             | 48   | 250  | 210.0       | 185.0      | 35.0        |

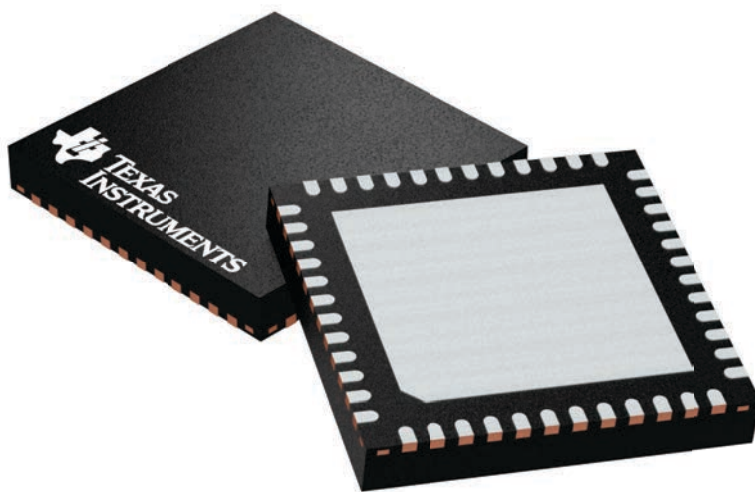
## GENERIC PACKAGE VIEW

**RGZ 48**

**VQFN - 1 mm max height**

7 x 7, 0.5 mm pitch

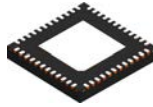
PLASTIC QUADFLAT PACK- NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4224671/A

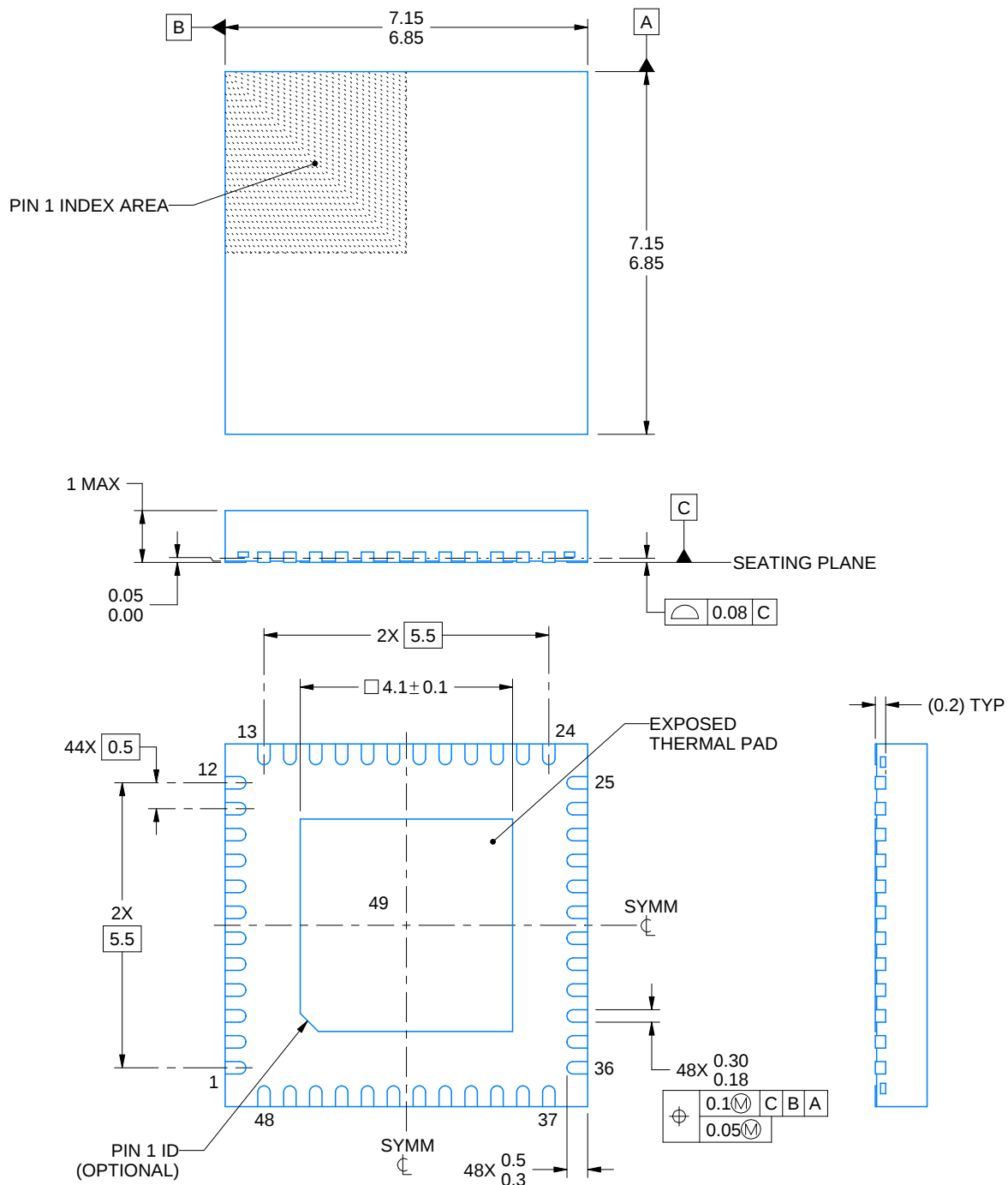
RGZ0048B



## PACKAGE OUTLINE

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



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### NOTES:

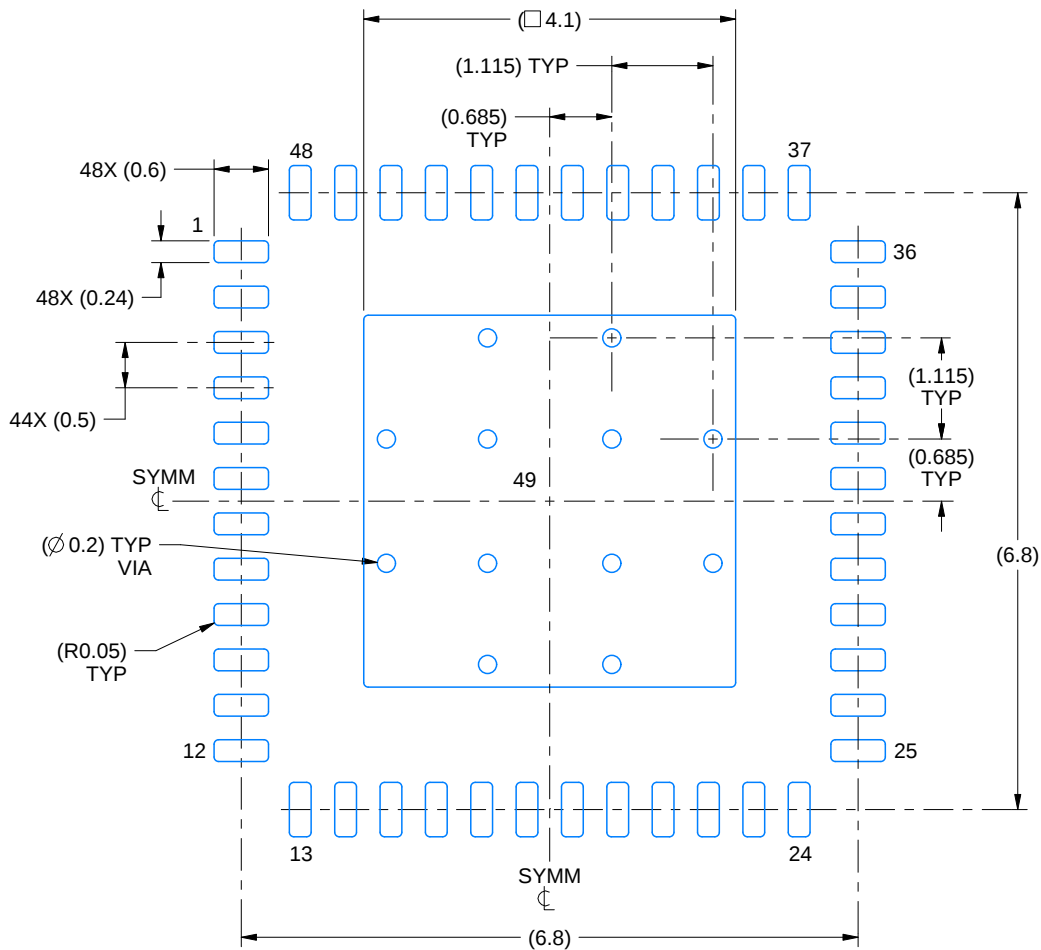
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

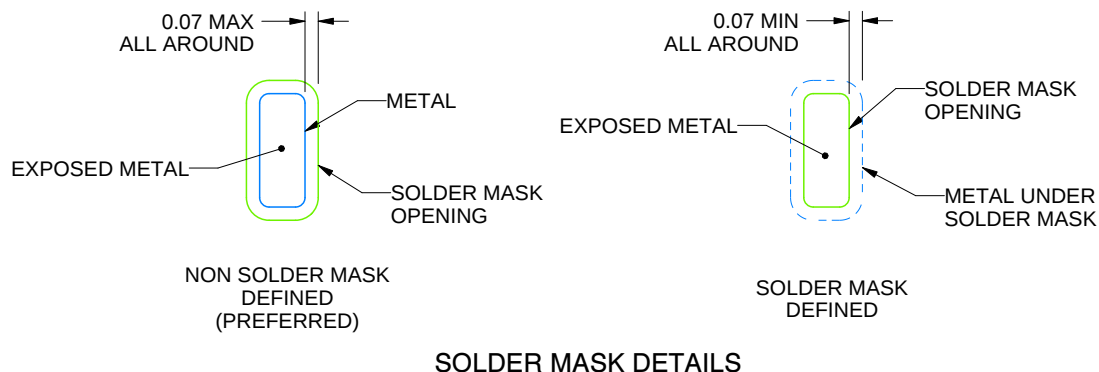
RGZ0048B

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:12X



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NOTES: (continued)

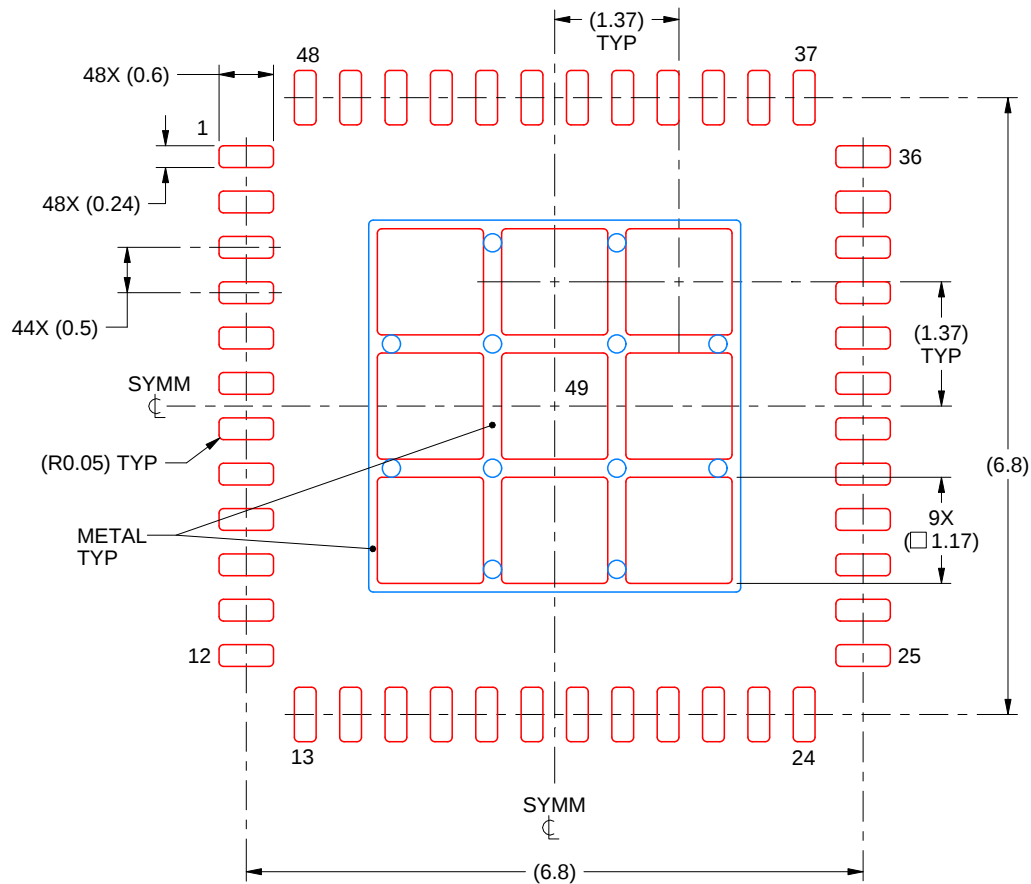
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

RGZ0048B

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



## SOLDER PASTE EXAMPLE BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 49  
73% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:12X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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